

ABSTRACT OF DISCLOSURE

A microelectronic device package including an electrically conductive lid having an attachment surface, a substrate having an attachment surface, at least one interconnect extending between the lid attachment surface and the substrate attachment surface, at least one microelectronic die disposed between the lid attachment surface and the substrate attachment surface, and the substrate having at least one first conductive trace extending between the electrically conductive first interconnect and the microelectronic die. The microelectronic device package allows for the use of the electrically conductive lid as a path for conducting signals (preferably power or ground) to and/or from a microelectronic die.